

RCJ160N20

Nch 200V 16A Power MOSFET

V_{DSS}	200V
R _{DS(on)} (Max.)	180m Ω
I _D	±16A
P_D	85W

Features

- 1) Low on-resistance.
- 2) Fast switching speed.
- 3) Drive circuits can be simple.
- 4) Parallel use is easy.
- 5) Pb-free lead plating; RoHS compliant
- 6) 100% Avalanche tested

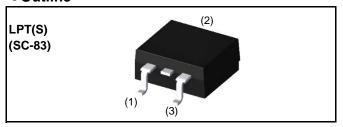
Application

Switching Power Supply

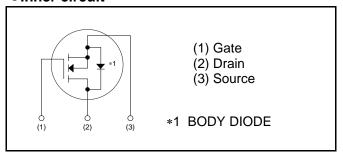
Automotive Motor Drive

Automotive Solenoid Drive

Outline



●Inner circuit



Packaging specifications

	Packaging	Taping
	Reel size (mm)	330
Typo	Tape width (mm)	24
Туре	Quantity (pcs)	1,000
	Taping code	TL
	Marking	RCJ160N20

● Absolute maximum ratings(T_a = 25°C)

Parameter	Symbol	Value	Unit	
Drain - Source voltage	V_{DSS}	200	V	
Operficación desir accessor	T _c = 25°C	I _D *1	±16	А
Continuous drain current	T _c = 100°C	I _D *1	±8.7	А
Pulsed drain current		I _{D,pulse} *2	±64	А
Gate - Source voltage		V_{GSS}	±30	V
Avalanche energy, single pulse		E _{AS} *3	20.7	mJ
Avalanche current		I _{AR} *3	8.0	А
$T_c = 25^{\circ}C$		P _D	85	W
Power dissipation $T_a = 25^{\circ}C^{*4}$		P _D	1.56	W
Junction temperature	T _j	150	°C	
Range of storage temperature		T _{stg}	-55 to +150	°C

●Thermal resistance

Parameter	Symbol	Values			Unit
- Farameter	Symbol	Min.	Тур.	Max.	Offic
Thermal resistance, junction - case	R_{thJC}	-	-	1.46	°C/W
Thermal resistance, junction - ambient *4	R_{thJA}	-	-	80	°C/W
Soldering temperature, wavesoldering for 10s	T _{sold}	-	-	265	°C

•Electrical characteristics($T_a = 25$ °C)

Parameter	Symbol	Conditions		Values		
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Drain - Source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V$, $I_D = 1mA$	200	-	-	V
		$V_{DS} = 200V, V_{GS} = 0V$ $T_{j} = 25^{\circ}C$	-	-	10	
Zero gate voltage drain current	I _{DSS}	$V_{DS} = 200V, V_{GS} = 0V$ $T_j = 125^{\circ}C$	-	-	100	μА
Gate - Source leakage current	I _{GSS}	$V_{GS} = \pm 30V, V_{DS} = 0V$	-	-	±100	nA
Gate threshold voltage	V _{GS (th)}	$V_{DS} = 10V$, $I_D = 1mA$	3.25	-	5.25	V
		$V_{GS} = 10V, I_D = 8.0A$	-	135	180	
Static drain - source on - state resistance	R _{DS(on)} *5	$V_{GS} = 10V, I_D = 8.0A$ $T_j = 125^{\circ}C$	-	295	410	mΩ
Forward transfer admittance	g fs	$V_{DS} = 10V, I_{D} = 8.0A$	4	8	-	S

●Electrical characteristics(T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
r ai ai i letei	Syllibol	Conditions	Min.	Тур.	Max.	Offic
Input capacitance	C_{iss}	$V_{GS} = 0V$	-	1370	-	
Output capacitance	C _{oss}	V _{DS} = 25V	-	95	-	pF
Reverse transfer capacitance	C_{rss}	f = 1MHz	-	50	-	
Turn - on delay time	t _{d(on)} *5	$V_{DD} \simeq 100 V$, $V_{GS} = 10 V$	-	27	-	
Rise time	t _r *5	$I_{D} = 8.0A$	-	47	-	ne
Turn - off delay time	t _{d(off)} *5	$R_L = 12.5\Omega$	-	42	-	ns
Fall time	t _f *5	$R_G = 10\Omega$	-	17	-	

• Gate Charge characteristics ($T_a = 25$ °C)

Parameter	Cymbol	Conditions	Values		Unit	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Total gate charge	Q_g^{*5}	V _{DD} ≃ 100V	-	26	-	
Gate - Source charge	Q _{gs} *5	I _D = 16A	-	10	-	nC
Gate - Drain charge	Q _{gd} *5	V _{GS} = 10V	-	11	-	
Gate plateau voltage	V _(plateau)	$V_{DD} \simeq 100V$, $I_D = 16A$	-	7.0	-	V

●Body diode electrical characteristics (Source-Drain)(T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
Parameter	Symbol Conditions		Min.	Тур.	Max.	Offic
Continuous source current	l _S *1	T _c = 25°C	-	1	16	А
Pulsed source current	I _{SM} *2	1 c = 25 C	-	-	64	Α
Forward voltage	V _{SD} *5	$V_{GS} = 0V, I_{S} = 16A$	-	-	1.5	V
Reverse recovery time	t _{rr} *5	I _S = 8.0A	-	85	-	ns
Reverse recovery charge	Q _{rr} *5	di/dt = 100A/μs	-	300	-	nC

^{*1} Limited only by maximum temperature allowed.

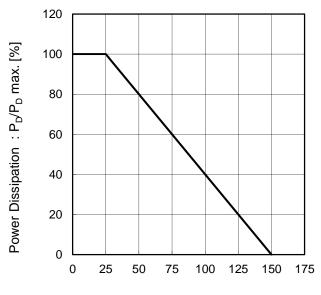
^{*2} Pw \leq 10 μ s, Duty cycle \leq 1%

^{*3} L $^{\simeq}$ 500 μ H, V_{DD} = 50V, Rg = 25 Ω , starting T $_{j}$ = 25°C

^{*4} Mounted on a epoxy PCB FR4 (25mm × 27mm × 0.8mm)

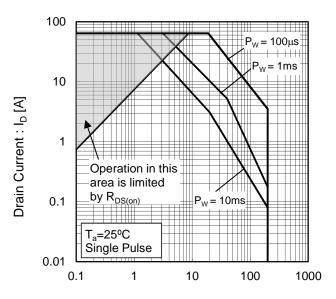
^{*5} Pulsed

Fig.1 Power Dissipation Derating Curve



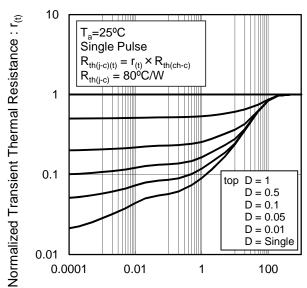
Junction Temperature : T_i [°C]

Fig.2 Maximum Safe Operating Area



Drain - Source Voltage : V_{DS} [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width



Pulse Width : $P_W[s]$

Fig.4 Avalanche Current vs Inductive Load

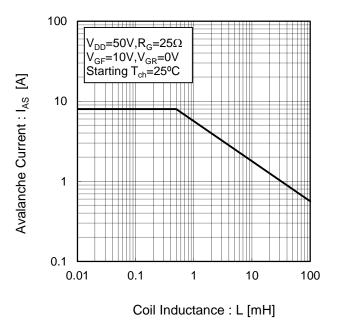
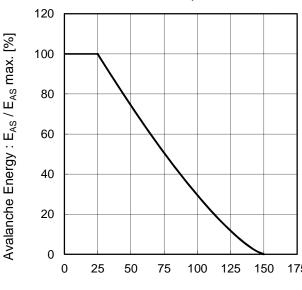
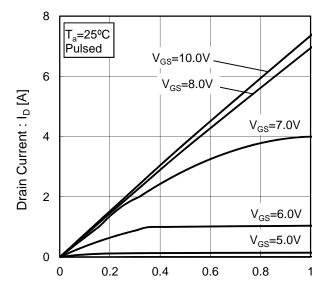


Fig.5 Avalanche Energy Derating Curve vs Junction Temperature



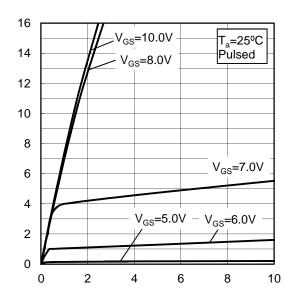
Junction Temperature : T_i [°C]

Fig.6 Typical Output Characteristics(I)



Drain - Source Voltage : $V_{DS}\left[V\right]$

Fig.7 Typical Output Characteristics(II)



Drain - Source Voltage : V_{DS} [V]

Drain Current : I_D [A]

Fig.8 Breakdown Voltage vs. Junction Temperature 280 Normarize Drain - Source Breakdown Voltage $V_{GS} = 0V$ 270 $I_D = 1 \text{mA}$ 260 250 240 230 220 210 200 190 180 -50 0 50 100 150 Junction Temperature : T_i [°C]

100 $V_{DS} = 10V$ 10 $V_{DS} = 10V$ $T_a = 125^{\circ}C$ $T_a = 75^{\circ}C$ $T_a = 25^{\circ}C$ $T_a = -25^{\circ}C$ $T_a = -25^{\circ}C$

0.001

0

2

Fig.9 Typical Transfer Characteristics

Gate - Source Voltage : V_{GS} [V]

6

8

10

Fig.10 Gate Threshold Voltage vs. Junction Temperature

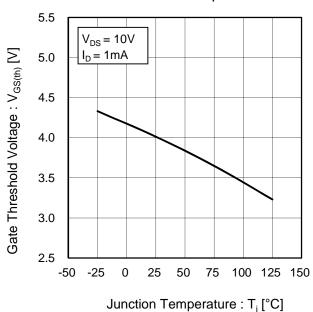
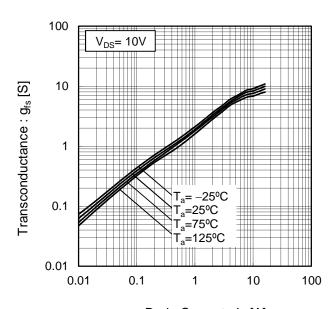


Fig.11 Transconductance vs. Drain Current



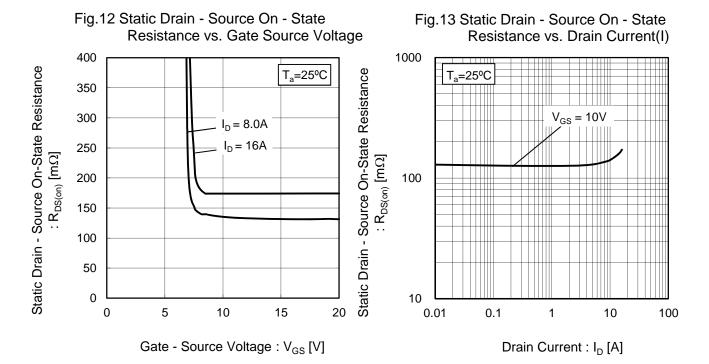
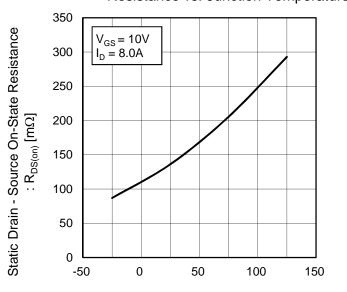
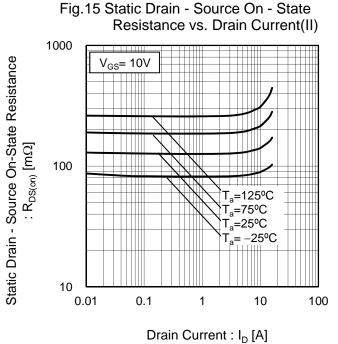


Fig.14 Static Drain - Source On - State Resistance vs. Junction Temperature



Junction Temperature : T_j [°C]

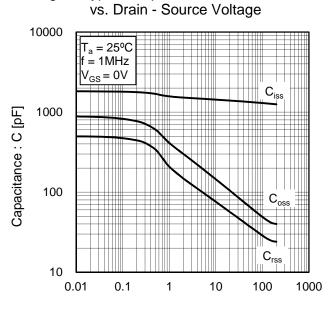


120 100 Drain Current Dissipation : I_D/I_D max. (%) 80 60 40 20 0 0 25 50 75 100 125 150 175

Junction Temperature : T_i [°C]

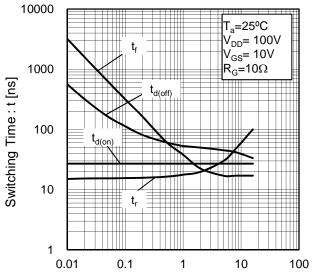
Fig.16 Drain Current Derating Curve

Fig.17 Typical Capacitance



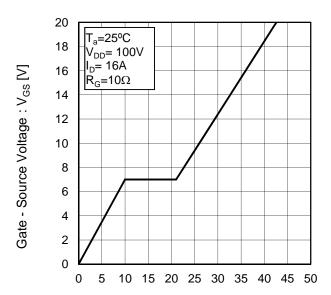
Drain - Source Voltage : V_{DS} [V]

Fig.18 Switching Characteristics

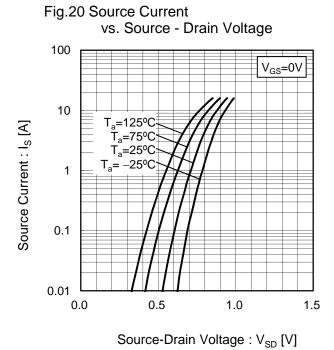


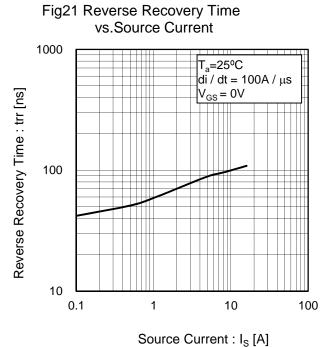
Drain Current : I_D [A]

Fig.19 Dynamic Input Characteristics



Total Gate Charge : Q_g [nC]





●Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

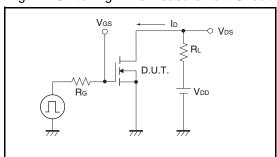


Fig.2-1 Gate Charge Measurement Circuit

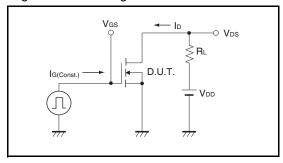


Fig.3-1 Avalanche Measurement Circuit

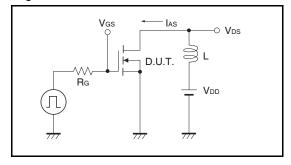


Fig.1-2 Switching Waveforms

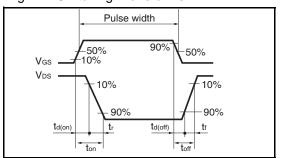


Fig.2-2 Gate Charge Waveform

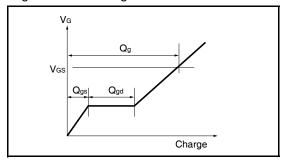
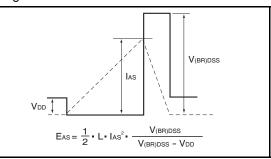
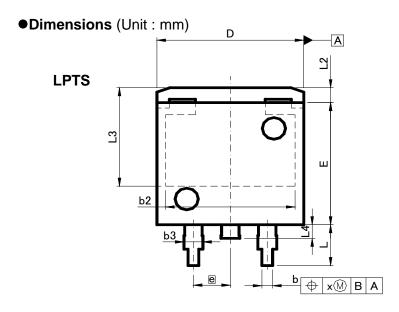
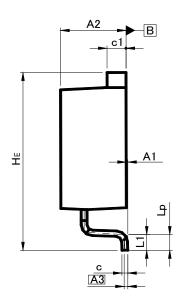
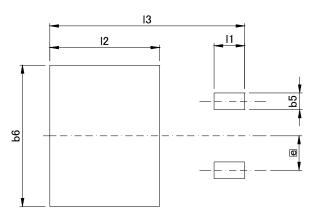


Fig.3-2 Avalanche Waveform









Patterm of terminal position areas

DIM	MILIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
A1	0.00	0.30	0	0.012
A2	4.30	4.70	0.169	0.185
A3	0.:	25	0.	01
b	0.68	0.98	0.027	0.039
b2	8.	90	0.	35
b3	1.14	1.44	0.045	0.057
С	0.30	0.60	0.012	0.024
c1	1.10	1.50	0.043	0.059
D	9.80	10.40	0.386	0.409
E	8.80	9.20	0.346	0.362
е	2.	54	0.	10
HE	12.80	13.40	0.504	0.528
L	2.70	3.30	0.106	0.13
L1	0.90	1.50	0.035	0.059
L2	1.	10	0.0)43
L3	7.	25	0.2	85
L4	1.	00	0.0	39
Lp	0.90	1.50	0.035	0.059
Х	_	0.25	_	0.01

DIM	MILIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
b5	-	1.23	ı	0.049
b6	-	10.40	-	0.409
11	-	2.10	-	0.083
12	-	7.55	-	0.297
13	_	13.40	_	0.528

Dimension in mm/inches

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CLASSIV	CLASSⅢ	CLASSⅢ	CLASSⅢ

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 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
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- 4. The Products are not subject to radiation-proof design.
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- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
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- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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 - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
 may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
 exceeding the recommended storage time period.
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